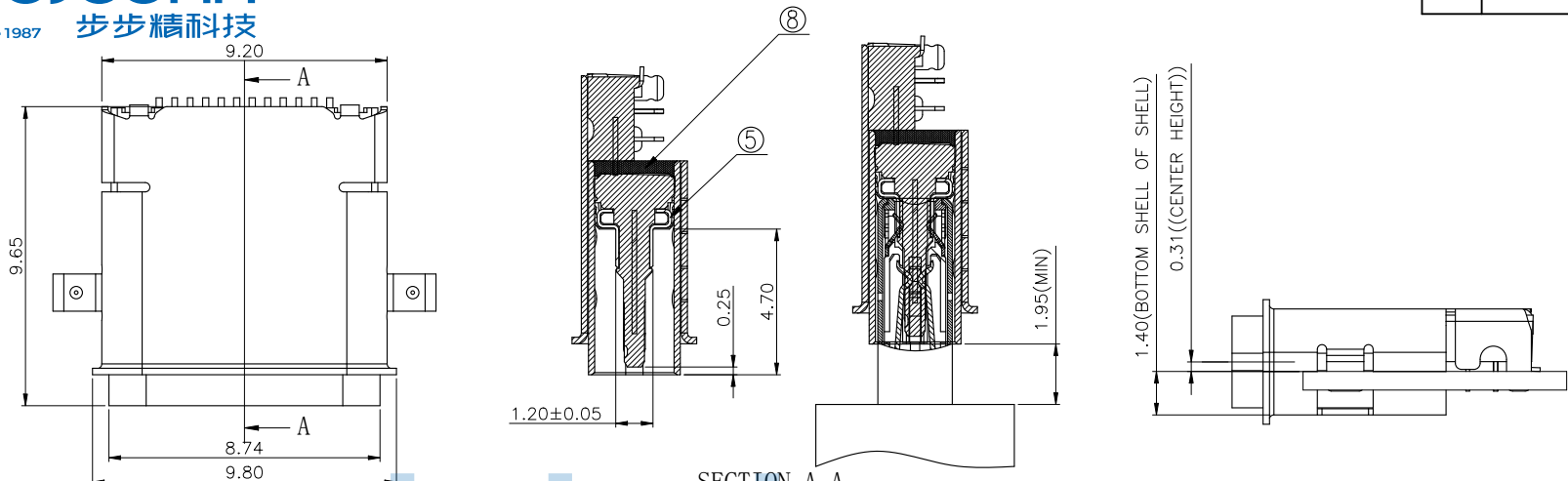
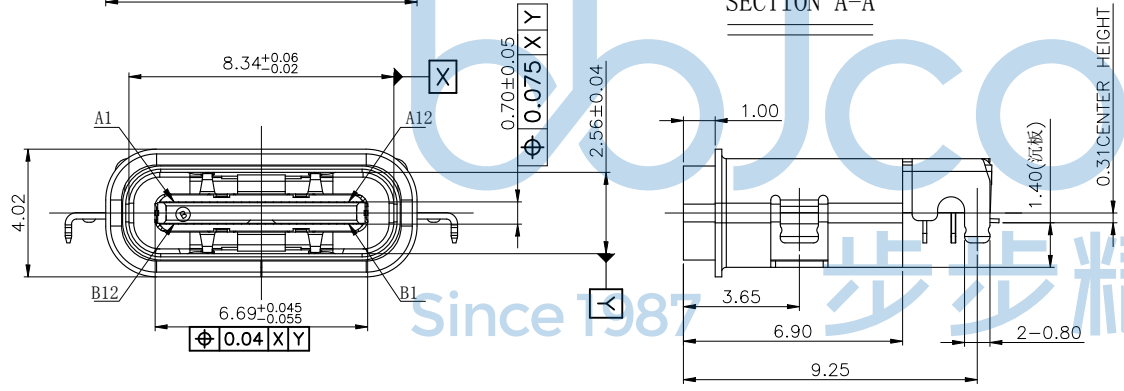


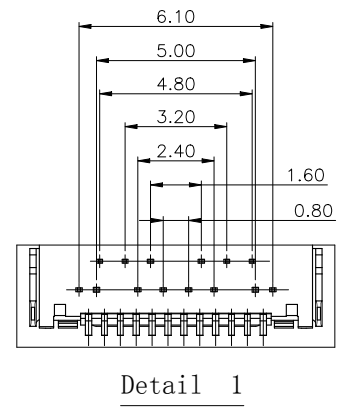
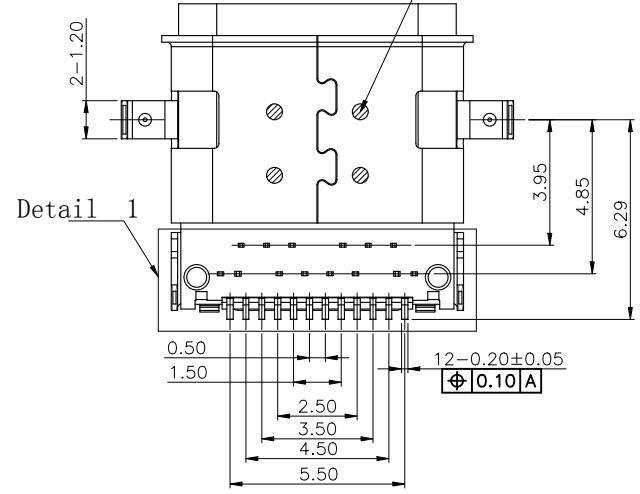
REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



SECTION A-A

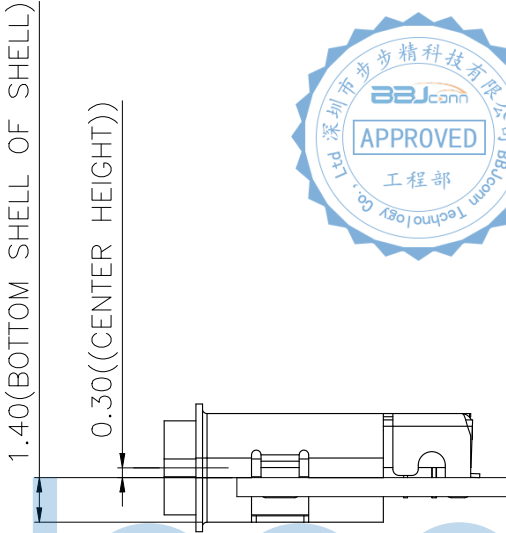
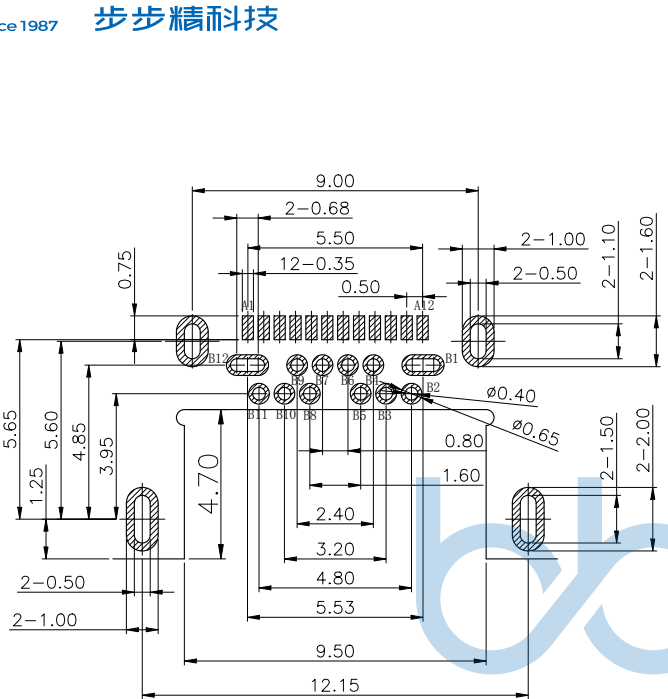


LASER WELDING POING



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APPD.	JM_Zheng	PJ. NO.: UC.01.52-1W-0031		SIZE: A4 DRW NO.:	
CHKD.	LYX	FINISH: SEE NOTES		MAT'L.: SEE NOTES	
PDWG.NO:	0228-1	DR.	TSP	SCALE: N/A	REV.: A0 UNIT: mm PAGE: 1/4

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

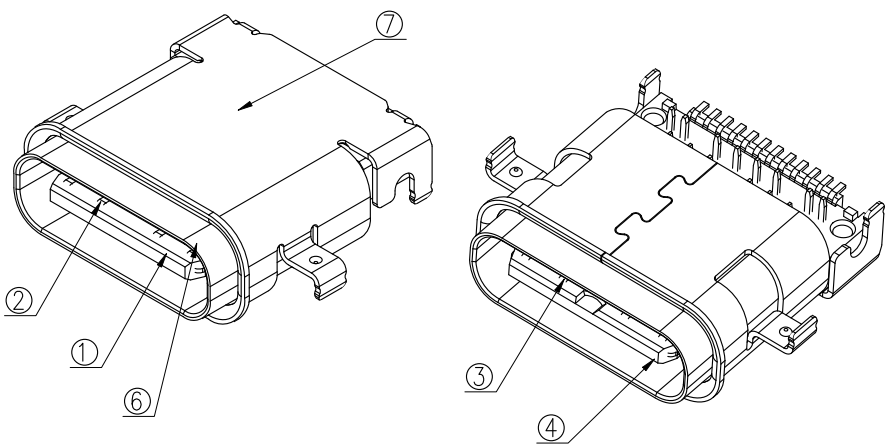


- MATERIAL:**
MOLDING: LCP UL94 V-0
CONTACT: COPPER ALLOY.
PLATED GOLD ON CONTACT AREA,
G/F GOLD ON SOLDER AREA,
50u" NICKEL PLATING OVER ALL.
SHELL: SUS304-H, T=0.30±0.03mm
50u" NICKEL PLATING OVER ALL.
EMI SHILD: SUS304-H, T=0.12±0.03mm
LATCH: SUS301-H, T=0.15±0.03mm
- MECHANICAL:**
INSERTION: 5°~20N.
EXTRACTION: 8°~20N.
DURABILITY: 10000 CYCLES
- ELECTRICAL:**
CURRENT: 5A MAX FOR VBUS;
1.25A MAX FOR OTHER.
VOLTAGE: 20VDC MAX
WITHSTANDING VOLTAGE: 100V AC.
CONTACT RESISTANCE: 40mΩ MAX.
INSULATION RESISTANCE: 100MΩ MIN.
- ENVIRONMENTAL**
TEMPERATURE RANGE: -30° C TO +80° C

RECOMMENDED P.C.B LAYOUT(Both sides are sample)
Tolerance: ±0.05, Thickness=0.60mm

Since 1987

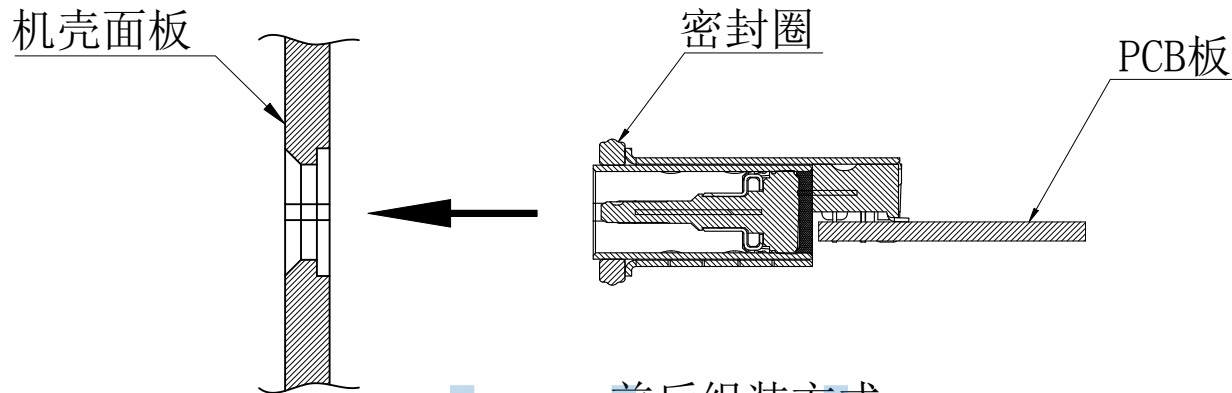
步步精科技



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APPD.	JM_Zheng	PJ. NO.: UC.01.52-1W-0031		SIZE: A4 DRW NO.:	
CHKD.	LYX	FINISH: SEE NOTES		MAT'L.: SEE NOTES	
PDWG.NO:	0228-1	DR.	TSP	SCALE: N/A	REV.: A0 UNIT: mm PAGE: 2/4

建议密封方式

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



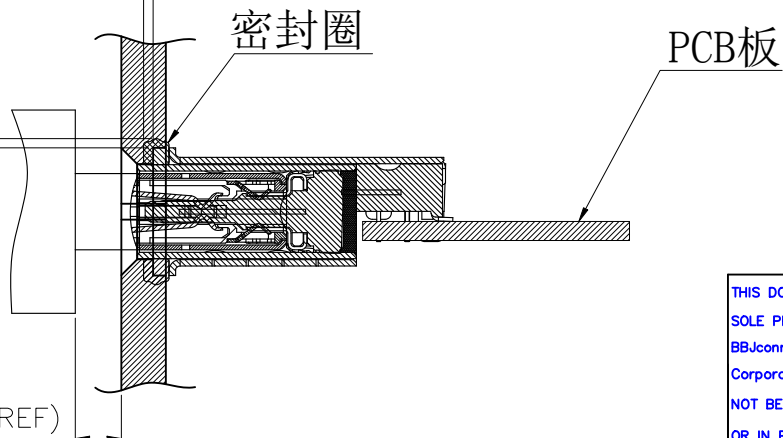
前后组装方式



机壳面板对密封圈与缩量0.30Min
(建议压缩量为密封圈直径大小40-50%)



机壳面板对密封圈与缩量0.30Min
(建议压缩量为密封圈直径大小40-50%)

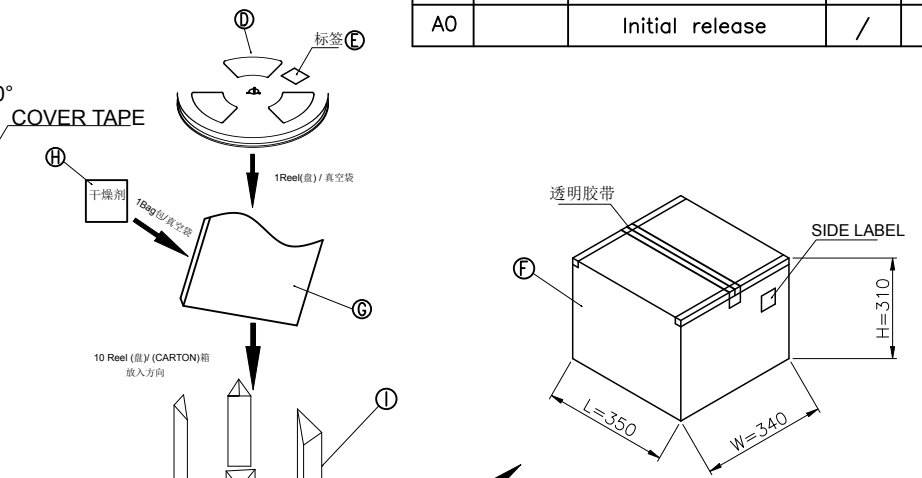
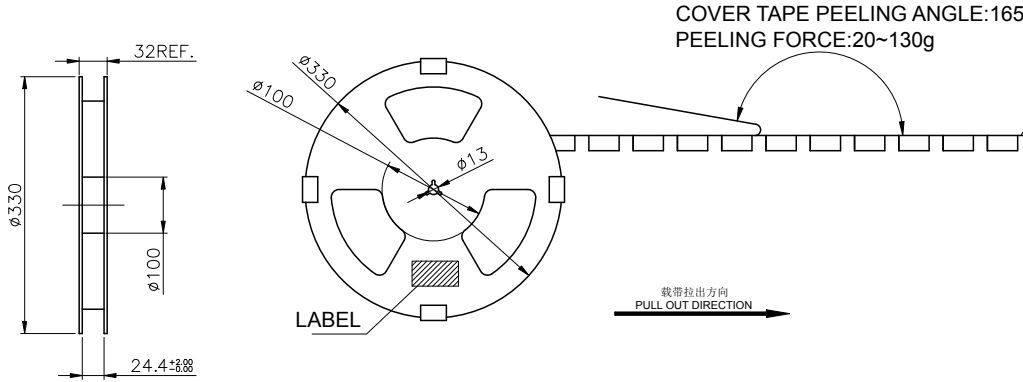


组装面板后公母头对插示意图



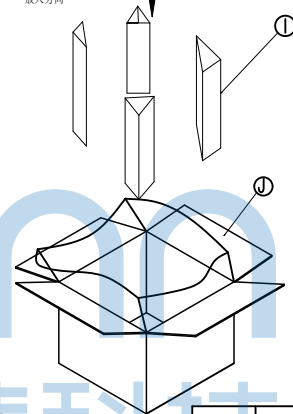
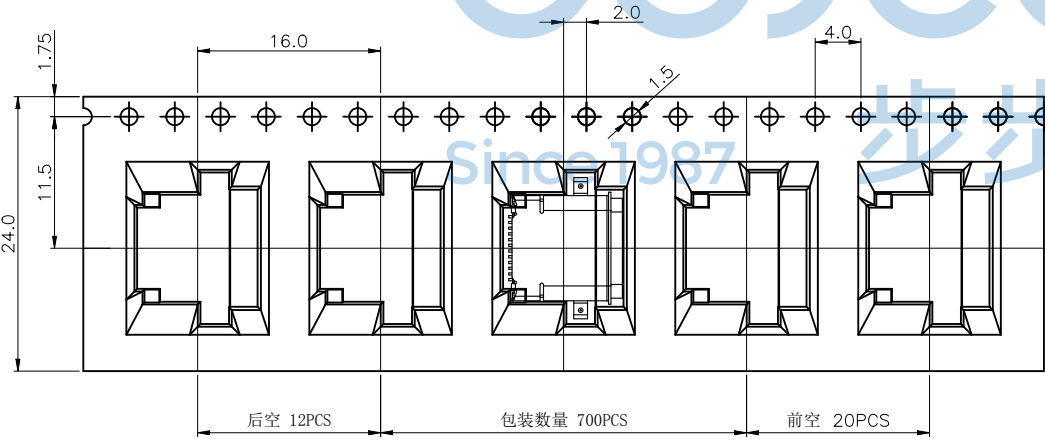
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APPD.	JM_Zheng	PJ. NO.: UC.01.52-1W-0031		SIZE: A4 DRW NO.:	
CHKD.	LYX	FINISH: SEE NOTES		MAT'L.: SEE NOTES	
PDWG.NO:	0228-1	DR.	TSP	SCALE: N/A	REV.: A0 UNIT: mm PAGE: 3/4

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



防水胶圈包装(两者独立包装)

5000	6	30000
PCS/BAG	BAG/CASE	PCS/CASE



J	PE袋	1	630L*620W
I	三角护柱	4	
H	干燥剂	10	
G	真空袋	10	500L*450W
F	纸箱	1	350L*340W*310H
E	标签	10	
D	REEL	10	
C	COVER TAPE	10	21.3m/m (1R/300M)
B	CARRIER TAPE	10	12511(L)*24(W)*0.4(T)
A	Phone Jack	7000	U501T24J4FZL2
NO	DESCRIPTION	Q'TA(PCS)	SPEC



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PDWG.NO: 0228-1

深圳市步步精科技有限公司

NAME: TYPE-C 24P 母座 四脚插 双外壳
端子DIP+SMT 沉板1.4 L=9.65 CH=0.31

PJ. NO.: UC.01.52-1W-0031
SIZE: A4 | DRW NO.:
FINISH: SEE NOTES | MAT'L.: SEE NOTES
SCALE: N/A | REV.: A0 | UNIT: mm | PAGE: 4/4

APPD.	JM_Zheng
CHKD.	LYX
DR.	TSP